ESCC

DOCUMENT CHANGE REQUEST

DCR number 292
Changes required for: General
Originator: Philippe Baviere
Date: 2006/10/12
Date sent: 2006/10/12
Organisation: CNES
Status: IMPLEMENTED

Title:	RF Inductors Fixed Miniature Moulded SMD, based on series MSCI 10K and MSCI 12K		
Number:	3201/008	Issue:	3

Other documents affected:

3201/009-4

Page:

Add a new Appendix A for manufacturer Microspire

Paragraph:

Add a new Appendix A for manufacturer Microspire

Original wording:

Proposed wording:

for Appendix A for Microspire :

....

Item Affected

Para 4.2.2, Deviations from Final Production Tests (Chart II)

Description of Deviations:

Para 9.2 Thermal Shock: Shall not be performed

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Item Affected

Para 4.2.3, Deviations from Burn in and Electrical Measurements (Chart III)

Description of Deviations:

Thermal Shock, in accordance with Para 9.2 of the Generic Specification for Chart II testing, shall be performed, for testing levels 'B' and 'C', immediately prior to Burn-in after the Initial Parameter Drift Value Measurements.

Justification:

In moving thermal shock to Chart III, one alectrical measurements is avoided. The drift is calculated on the sequence Thermal shock + Burn-in and the thermal shock failures are counted for the PDA calculation.

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See datas of the last VOQ for MSCI and of the qualification report for SESI inductors.
For clarification of when Thermal shock is performed and that it applies to both testing levels.
There is no need to mention the PDA in the appendix as, by definition, the PDA applies to all tests in Chart III.

Attachments:

N/A

Modifications:

N/A

Approval signature:

Date signed:

2006-10-12